



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20240520008.1
Datasheet for OPAx130
Change Notification

Date: May 23, 2024

Dear Customer:

This is a notice of change to a product data sheet for a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within **30 days** of this notification.

The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the Change Management team.

Sincerely,

Change Management Team
SC Business Services

20240520008.1
Data Sheet Change Notification
Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
OPA130UA	NULL
OPA130UA/2K5	NULL
OPA2130UA	NULL
OPA2130UA/2K5	NULL
OPA4130UA	NULL
OPA4130UA/2K5	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:		20240520008.1			PCN Date:		May 23, 2024	
Title:		Datasheet for OPAx130						
Customer Contact:		Change Management team			Dept:		Quality Services	
Proposed 1st Ship Date:		August 21, 2024						
Change Type:								
☐	Assembly Site			☐	Design		☐	Wafer Bump Material
☐	Assembly Process			☒	Data Sheet		☐	Wafer Bump Process
☐	Assembly Materials			☐	Part number change		☐	Wafer Fab Site
☐	Mechanical Specification			☐	Test Site		☐	Wafer Fab Materials
☐	Packing/Shipping/Labeling			☐	Test Process		☐	Wafer Fab Process

PCN Details

Description of Change:

The product datasheet(s) is being updated as summarized below.
The following change history provides further details.



OPA130, OPA2130, OPA4130
SBOS053B – MAY 1998 – REVISED MAY 2024

Changes from Revision A (March 2006) to Revision B (May 2024)

Page

• Updated the numbering format for tables, figures, and cross-references throughout document.....	1
• Deleted DIP packages from data sheet.....	1
• Updated open-loop gain to match <i>Electrical Characteristics</i> in <i>Features</i>	1
• Added <i>Applications</i>	1
• Updated pin diagrams, added pin function tables, and moved all to new <i>Pin Configuration and Functions</i>	3
• Updated input voltage in <i>Absolute Maximum Ratings</i>	5
• Added input current and related footnote to <i>Absolute Maximum Ratings</i>	5
• Added <i>Recommended Operating Conditions</i> and <i>Thermal Information</i>	5
• Changed format of <i>Electrical Characteristics</i> to latest standard.....	7
• Updated nominal conditions in the header of <i>Electrical Characteristics</i>	7
• Deleted channel separation specification.....	7
• Updated common-mode voltage.....	7
• Updated common-mode rejection ratio and common-mode input impedance test conditions.....	7
• Changed differential input impedance from $10^{13}\Omega \parallel 1\text{pF}$ to $10^{13}\Omega \parallel 5\text{pF}$	7
• Changed common-mode input impedance from $10^{13}\Omega \parallel 3\text{pF}$ to $10^{13}\Omega \parallel 4.3\text{pF}$	7
• Updated open loop voltage gain MIN and TYP values for $R_L = 10\text{k}\Omega$ and $R_L = 2\text{k}\Omega$	7
• Updated settling time test condition.....	7
• Moved voltage output negative MIN values to MAX values.....	7
• Changed capacitive load drive specification from 10nF to See <i>Typical Characteristics</i>	7
• Deleted note 1 from <i>Electrical Characteristics</i>	7
• Deleted Figure 5-7, <i>A_{OL}, CMR, PSR vs Temperature</i>	8
• Updated Figure 5-17, <i>Small-Signal Overshoot vs Load Capacitance</i>	8
• Updated text in <i>Offset Voltage Trim</i>	11
• Changed Figure 1, <i>OPA130 Offset Voltage Trim Circuit</i> , to Figure 6-1, <i>Second-Order Low-Pass Filter</i>	11

The datasheet number will be changing.

Device Family	Change From:	Change To:
OPAx130	SBOS053A	SBOS053B

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/OPA130>

Reason for Change:

Supply Continuity

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):			
These changes are part of our multiyear plan to transition products from our 150-millimeter factories to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity. Datasheet changes associated with PCN 20240202010			
Changes to product identification resulting from this PCN:			
None.			
Product Affected:			
OPA130UA	OPA130UA/2K5	OPA2130UA	OPA2130UA/2K5
OPA4130UA	OPA4130UA/2K5		

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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